

KLM306X

SOP4 ZERO-CROSS TRIAC

PHOTOCOUPLER

SOP4 过零双向可控硅光电耦合器



* 本文中包含的信息反映了具有代表性的使用场景，仅供技术参考。

The information contained in this document reflects representative usage scenarios and is intended for technical reference only.

* 本文中提到的产品型号和规格如有更改或改进，恕不另行通知。在生产使用之前，客户应参考产品规格书的最新数据表。

Product models and specifications mentioned in this document are subject to change or improvement without notice. Customers should refer to the latest data sheets in the product specifications prior to production use.

* 在使用本文中引用的产品时，请确保产品在数据手册中规定的环境和电气限制范围内运行。如果客户使用超过指定的限制，晶台将不会对任何后续问题负责。

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* 本文档中的信息适用于电子元器件应用中的典型用法。如有任何特殊用途，请向晶台咨询，以获得进一步的帮助。

The information in this document applies to typical use in electronic component applications. For special applications, please contact Kinglight for further assistance.

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1. 产品特点 Product features

- 无卤素 (溴<900ppm, 氯<900ppm, 溴+氯<1500ppm)
Halogens free (Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- 峰值击穿电压 Peak breakdown voltage
KLM306X: 600V
- 输入与输出间高隔离电压(Viso=3750 V rms)
High isolation voltage between inputs and output (Viso=3750 V rms)
- 过零电压 Zero voltage crossing
- 符合欧盟REACH法规 Compliance with EU REACH
- 无Pb且符合ROHS标准 Pb free and RoHS compliant

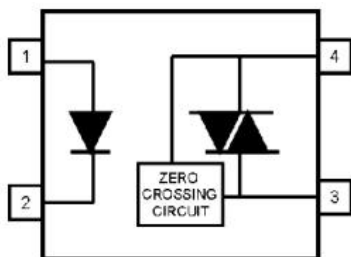
2. 产品描述 Product Description

- KLM306X 器件包括一个砷化镓红外发射二极管和一个单晶硅芯片的过零光电双向晶闸管组成，属于零交叉双向可控硅驱动器光耦
The KLM306X device consists of a GaAs infrared emitting diode and a single crystal silicon chip zero-cross triac transistor. The KLM306X device is a zero-crossing triac photocoupler.
- 它被设计用于与分立功率双向可控硅开关配合使用，将逻辑系统连接到由 110 至 240 VAC 线路供电的设备，如固态继电器、工业控制装置、电机、螺线管和消费电器、高速风筒 等
It is designed to use with a discrete power triac in the interface of logic systems to equipment powered from 110 to 240 VAC lines, such as solid-state relays, industrial controls, motors, solenoids and consumer appliances, high-speed blower, etc.

3. 产品应用 Product Applications

- 电磁阀/阀门控制器 Solenoid/valve controls
- 灯光控制 Light controls
- 静态电源开关 Static power switch
- 交流电机驱动器 AC motor drivers
- 电动机接触器 E.M. contactors
- 温度控制器 Temperature controls
- 交流电机启动器 AC Motor starters
- 高速风筒 High-speed blower

4. 功能图 Functional Diagram



引脚配置 Pin Configuration

1. 阳极Anode
2. 阴极Cathode
3. 终端Terminal
4. 终端Terminal

5. 光电特性 Electrical-Optical characteristics

• 最大限度额定值(温度=25°C) Absolute Maximum Ratings(Ta=25°C)

参数 Parameter		符号 Symbol	额定值 Rated Value	单位 Unit
输入 Input	正向电流 Forward current	I_F	60	mA
	峰值正向电流 Peak forward current (1us pulse, 300pps)	$I_{F(PK)}$	1	A
	反向电压 Reverse voltage	V_R	6	V
	功耗 Power dissipation	P_D	100	mW
输出 Output	断态输出端电压 Off-state Output Terminal Voltage	V_{DRM}	600	V
	导通有效值电流 On-State RMS Current	$I_{T(RMS)}$	70	mA
	功耗 Power dissipation	P_C	300	mW
隔离电压 (1*) Isolation Voltage		V_{iso}	3750	Vrms
工作温度 Operating temperature		T_{OPR}	-40 to +110	°C
储存温度 Storage temperature		T_{STG}	-55 to +150	°C
焊接温度 (2*) Soldering temperature		T_{SOL}	260	°C

附注 (Notes):

1* 交流电源1分钟内, 相对湿度在40~60%RH环境下, 隔离电压测试时, 1&2脚短接, 3&4脚短接
AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1&2 are shorted together, and pins 3&4 are shorted together.

2* 焊接时间为10秒 Soldering time is 10 seconds

6. 电气特性(Ta=25°C,除非另有规定)

Electrical Characteristics(Ta=25°C unless specified otherwise)

参数 Parameter		符号 Symbol	最小值 Min.	规格值 Typ.	最大值 Max.	单位 Unit	条件 Condition
输入 In put	正向电压 Forward voltage	V_F	-	-	1.5	V	$I_F=30\text{mA}$
	反向电流 Reverse current	I_R	-	-	10	μA	$V_R=6\text{V}$
输出 Out put	断态峰值电流 Peak Blocking Current	I_{DRM1}	-	-	100	nA	$V_{\text{DRM}} = \text{Rated}$ V_{DRM} $I_F = 0\text{mA}$
	峰值导通电压 Peak On-state Voltage	V_{TM}	-	-	3	V	$I_{\text{TM}}=100\text{mA}$ peak
	断态电压临界上升率 Critical Rate of Rise off- state Voltage	dv/dt	1000	-	-	V/ μs	
	抑制电压 (MT1-MT2 电压 高于该电压时器件不会触 发) Inhibit Voltage (MT1-MT2 voltage above which devicewill not trigger)	V_{INH}	-	-	20	V	$I_F = \text{Rated } I_{\text{FT}}$
抑制状态下的漏电流 Leakage Current in Inhibited State	I_{DRM2}	-	-	1000	μA	$I_F = \text{Rated } I_{\text{FT}}$, $V_{\text{DRM}} = \text{Rated}$ V_{DRM} , off state	

• 附注(Notes):

Ta=25°C时的规格值 Typical values at Ta = 25°C

- 传输特性 (Ta=25°C, 除非另有规定)

Transfer Characteristics (Ta=25°C unless specified otherwise)

参数 Parameter		符号 Symbol	最小值 Min.	规格值 Typ.	最大值 Max.	单位 Unit	条件 Condition
LED触发电流 LED Trigger Current	KLM3062	I_{FT}	-	-	10	mA	主端子电压=3V Main terminal Voltage=3V *
	KLM3063		-	-	5		
	KLM3064		-	-	3		
保持电流 Holding Current		I_H	-	280	-	μA	

附注(Notes):

* 所有器件都保证在小于或等于最大 I_{FT} 的 I_F 值触发. 因此, 建议操作 I_F 在最大 I_{FT} (KLM3062 10mA、KLM3063 5mA、KLM3064 3mA)和绝对最大 I_F (60mA)之间

All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT} . Therefore, Recommended operating I_F lies between max I_{FT} (10 mA for KLM3062, 5 mA for KLM3063, 3 mA for KLM3064) and absolute maximum I_F (60 mA).

7. 可靠性试验 Reliability Test

序号 NO.	试验项目 Test Items	参考标准 Reference	试验条件 Test conditions	试验过程 Test process	试验数 Qty.(pcs)	允收水准 LTPD
1	温度循环 TC	JESD22-A104C	H:125±5°C 15min J5min L:-55±5°C 15min	300cycle	45	0/45
2	高温操作寿命 HTOL	JESD22-A108C	HTOL@110°±5C IF=15mA Ic=AC 20mA	168、500、 1000hrs	45	0/45
3	高温反向偏压 HTRB	JESD22-A108C	HTRB@100±5°C Vce=480V	168、500、 1000hrs	45	0/45
4	温湿度反向偏 压寿命试验 H3TRB	JESD22-A101- B	H3TRB@ 85+5/-2°C 、85±5%RH Vce=100V	168、500、 1000hrs	45	0/45
5	压力锅 PCT	JESD22-A102- C	Ta=121±5°C, 100±5%RH, 2atm	96hrs	45	0/45
6	高温储存 HTS	JESD22-A103C	HTS@125±5°C	168、500、 1000hrs	45	0/45
7	低温储存 LTS	JESD22-A119	LTS@-55±5°C	168、500、 1000hrs	45	0/45
8	耐锡热试验 RSH	JESD22-B106C	RSH@260±5°C	10sec*3times	45	0/45
9	可焊性 SD	JESD22-B102D	Pb-free@ 245±5°C	3sec*1times	22	0/22
备注 Remarks	以上试验项目如与客户试验要求存在差异或者特殊客户特殊要求的,可根据实际情况按照客户的要求进行试 作,客户未要求依我司试验标准试作,不同产品使用不同电流进行测试 All the tests should be performed according to customers' actual requirements, while difference of test standard or special requirements exist. Otherwise, all the tests are performed according to the standard listed above. Different current is applied to the tests of different product models					

8. 特性曲线 Characteristic Curves

图1. 正向电流与正向电压的关系

Figure 1. Forward Current vs Forward Voltage

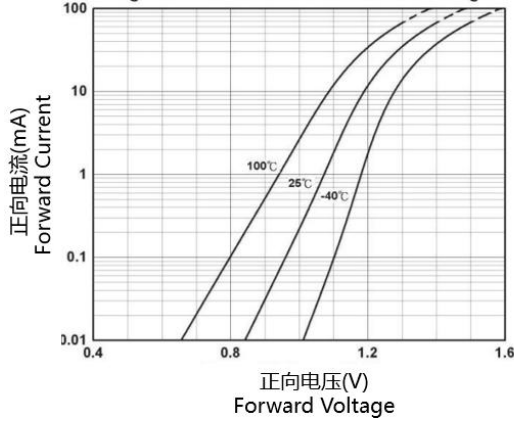


图2. 导通特性

Figure 2. On-State Characteristics

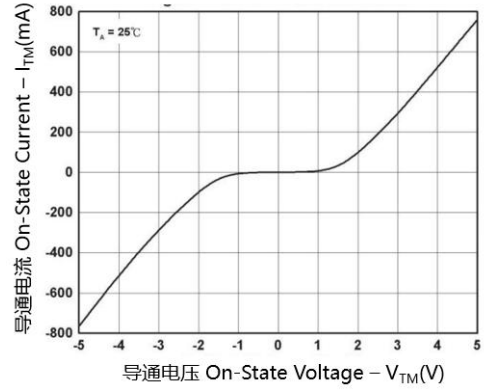


图3. 保持电流 vs 环境温度的关系

Figure 3. Normalized Holding Current vs Ambient Temperature

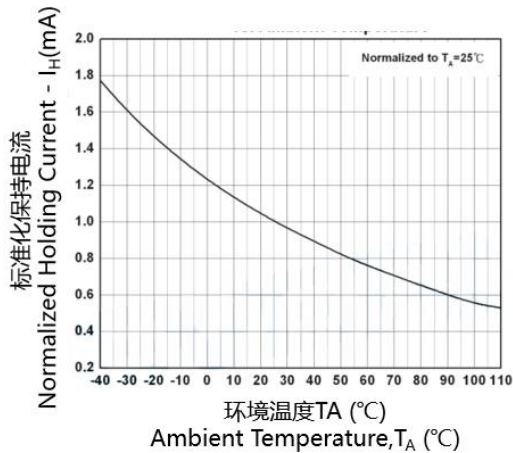


图4. 触发所需LED电流 vs LED脉冲宽度的关系

Figure 4. LED Current Required to Trigger vs LED Pulse Width

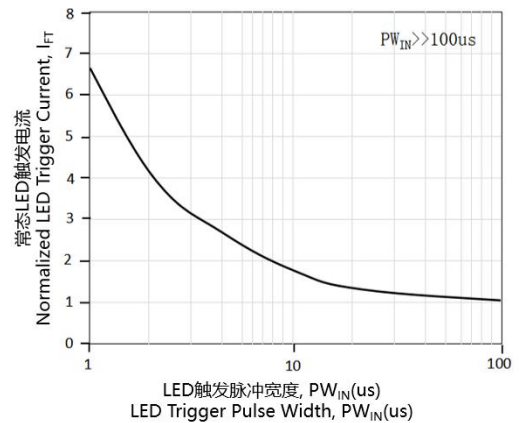


图5. 漏电流 vs 环境温度的关系

Figure 5. Leakage Current vs Ambient Temperature

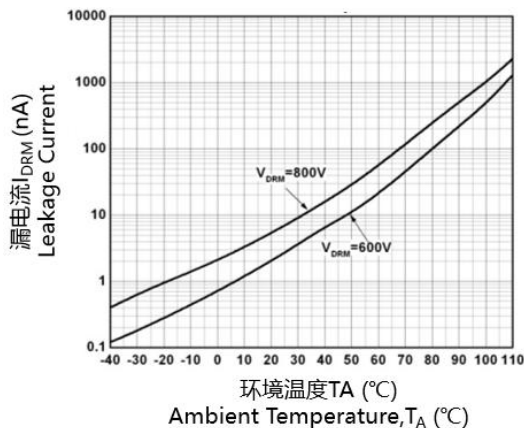


图6. LED触发电流 vs 环境温度的关系

Figure 6. LED Trigger Current vs Ambient Temperature

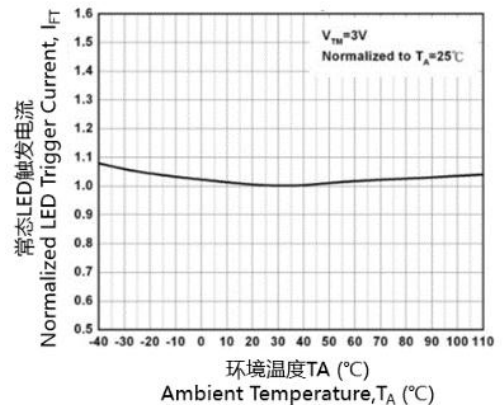


图7.关闭状态输出端电压 vs 环境温度的关系
Figure 7. Off-State Output Terminal Voltage vs Ambient Temperature

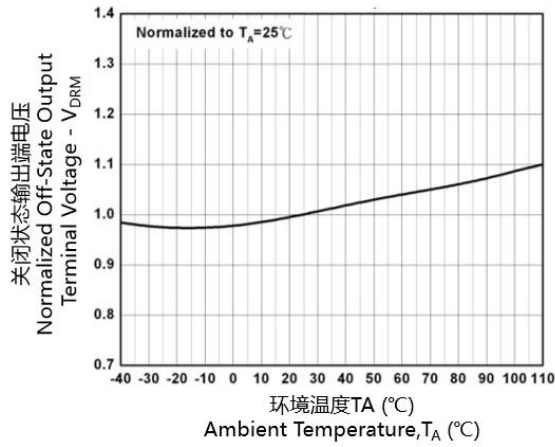


图8. 抑制状态下的漏电流 vs 环境温度的关系
Figure 8. Leakage Current in Inhibit State vs Ambient Temperature

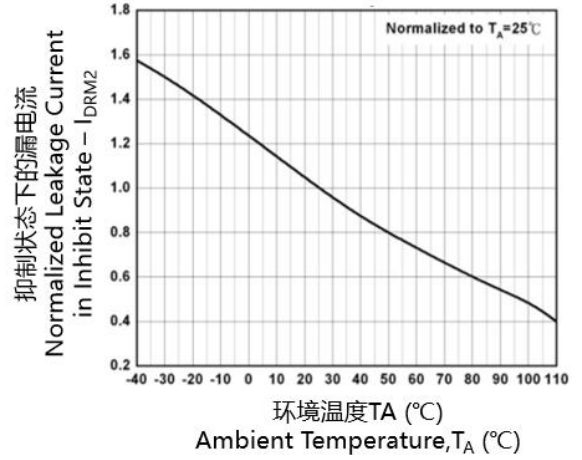


图9. 抑制电压 vs 环境温度的关系
Figure 9. Inhibit Voltage vs Ambient Temperature

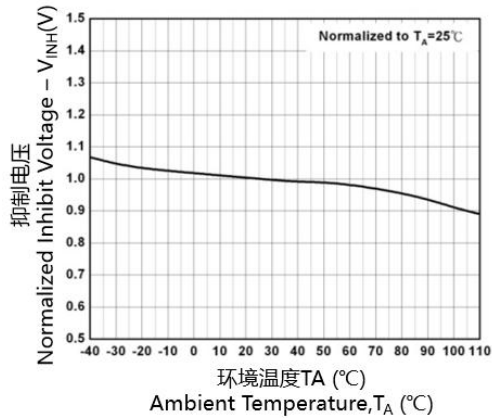
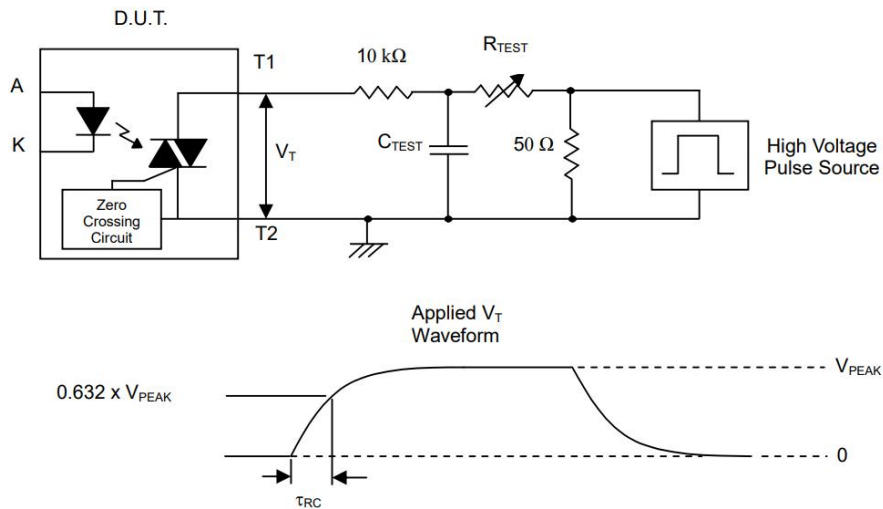


图10.静态dv/dt测试电流和波形 Static dv/dt Test Circuit & Waveform



测量方法 Measurement Method

高压脉冲设置为所需的 V_{PEAK} 值, 并通过上述RC电路应用于D.U.T.输出值, 不应用LED电流, 使用X100范围探头监视波形 V_T , 通过改变 R_{TEST} , dv/dt (斜率)增加, 直到DU被观察到触发(波形崩溃)。 dv/dt 随后下降, 直到D.U.T. 停止触发, 此时记录 τ_{RC} , 计算 $dv/dt=0.632 \cdot V_{PEAK} / \tau_{RC}$

The high voltage pulse is set to the required V_{PEAK} value and applied to the D.U.T. output side through the RC circuit above. LED current is not applied. The waveform V_T is monitored using a x100 scope probe. By varying R_{TEST} , the dv/dt (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The dv/dt is then decreased until the D.U.T. stops triggering. At this point, τ_{RC} is recorded and the dv/dt calculated. $dv/dt=0.632 \cdot V_{PEAK} / \tau_{RC}$

例如, KLM306X系列的 $V_{PEAK}=600V$, dv/dt 值的计算公式如下:

For example, $V_{PEAK} = 600V$ for KLM306X series. The dv/dt value is calculated as follows:

$$dv/dt = 0.632 \cdot 600 / \tau_{RC}$$

9. 订单信息 Order Information

- 材料编号 Part Number

KLM306X-Z-V

附注(Notes):

X = 零件编号(2、3 或 4) Part No. (2 , 3 or 4)

Z = 料带和卷轴选项(TA、TB 或 无)

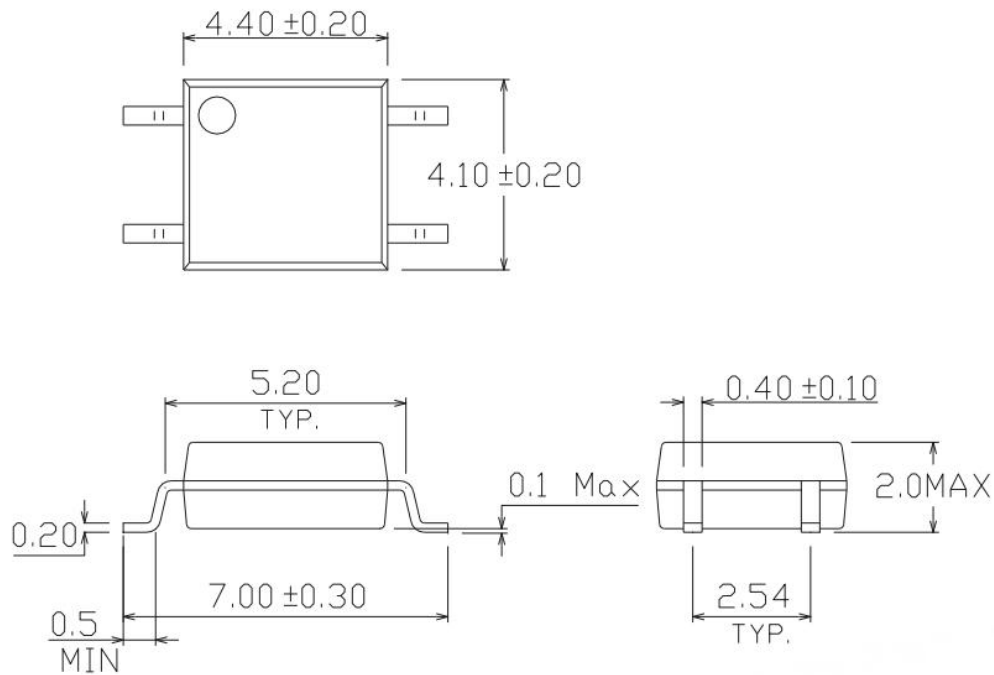
Tape and reel option (TA, TB or None)

V = 表示VDE标识(客户指定镭射字符才加"V")

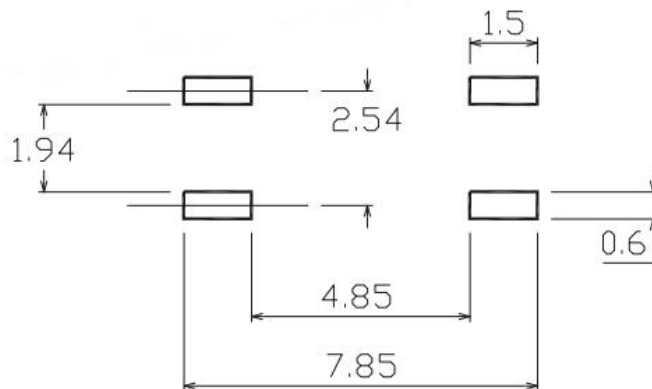
VDE (Only add "V" to laser characters specified by the customer)

选项 Option	描述 Description	包装数量 Packing quantity
无 None	标准DIP-4 Standard DIP-4	每管100pcs 100 units per tube
无 None	标准DIP-4 + VDE Standard DIP-4 + VDE optional	每管100pcs 100 units per tube
TA	TA载带和卷轴选项 TA Tape & reel option	每卷3000pcs 3000 units per reel
TB	TB载带和卷轴选项 TB Tape & reel option	每卷3000pcs 3000 units per reel
TA-V	TA载带和卷轴选项 + VDE TA Tape & reel option + VDE optional	每卷3000pcs 3000 units per reel
TB-V	TB载带和卷轴选项 + VDE TB Tape & reel option + VDE optional	每卷3000pcs 3000 units per reel
/	内盒装: 每盒3盘 Inner box packaging: 3reels/box	每盒9000pcs 9000pcs per box
/	每箱装: 10个内盒 Pack per Carton: 10inner boxes	每箱90000pcs 90000pcs per Carton

10. 封装尺寸(单位:毫米) Package Drawing(Unit:mm)



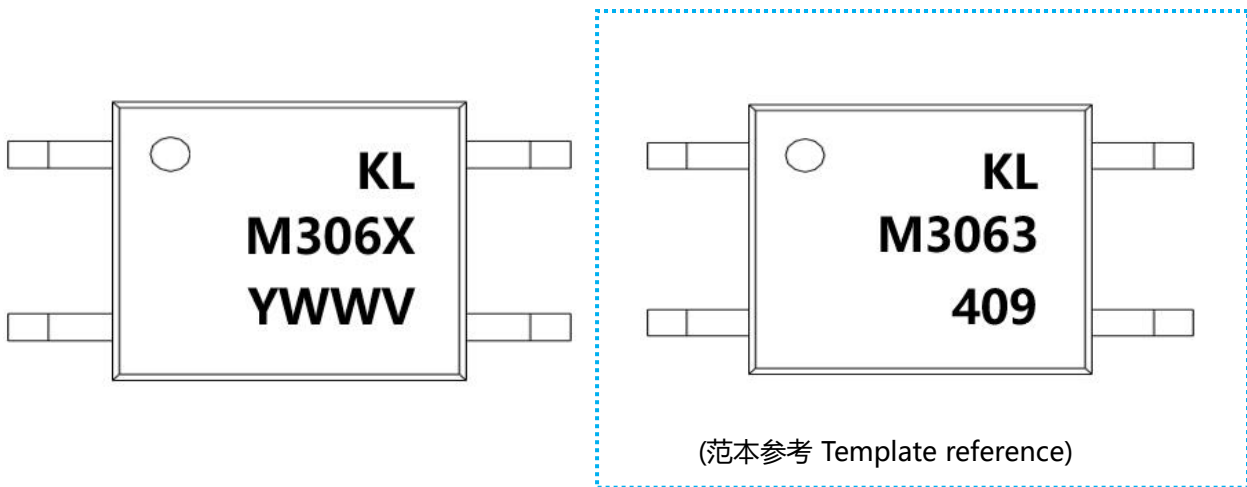
- 表面贴片类型PIN脚焊盘布局 Surface patch type PIN foot pad layout



备注 Notes

- 建议焊盘尺寸仅供参考 Suggested pad dimension is just for reference only
- 请根据个人需要修改焊盘尺寸 Please modify the pad dimension based on individual need

11. 设备标记 Device marking

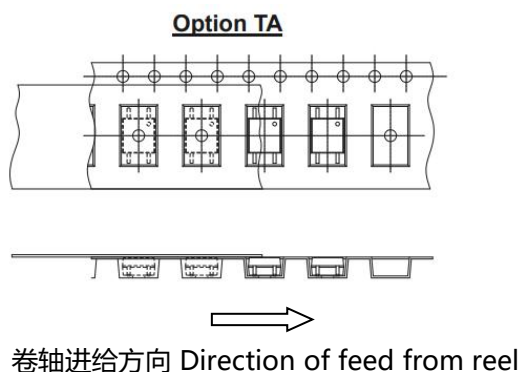


附注(Notes):

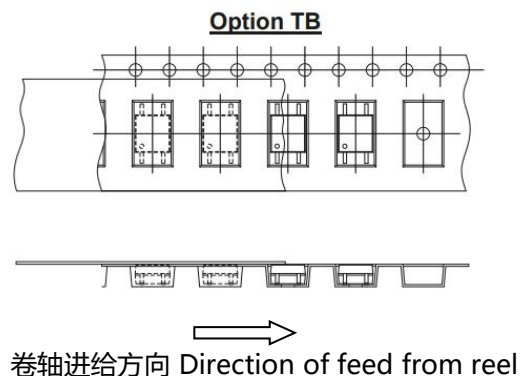
- KL = 表示晶台光电有限公司 Denotes KingLight
- M306X = 表示材料部件号 Denotes Device Part Number
X表示零件编号(2、3 或 4) Part No. (2, 3 or 4)
- Y = 表示1位年份代码Denotes 1 digit Year code
- WW = 表示2位周别代码Denotes 2 digit Week code
- V = 表示VDE标识(客户指定镭射字符才加"V")
VDE (Only add "V" to laser characters specified by the customer)

12. 料带和卷轴包装规格 Tape & Reel Packing Specifications

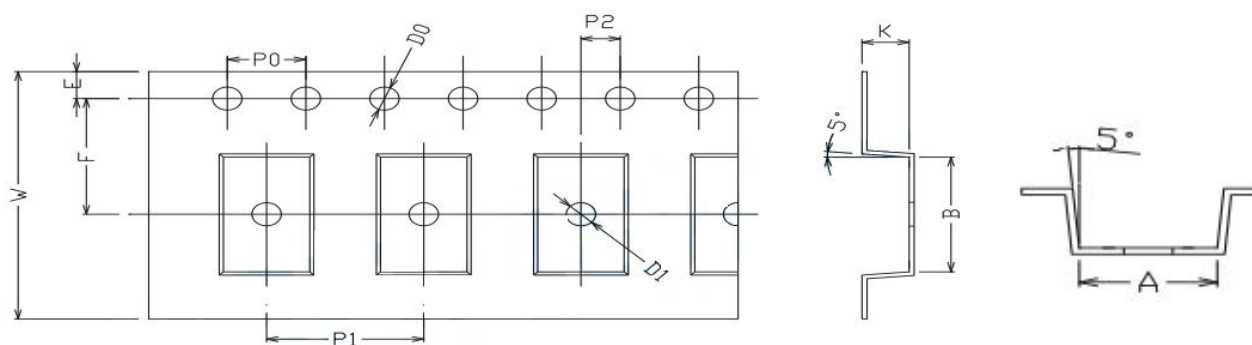
• 选择TA Option TA



• 选择TB Option TB



料带尺寸 Material belt size



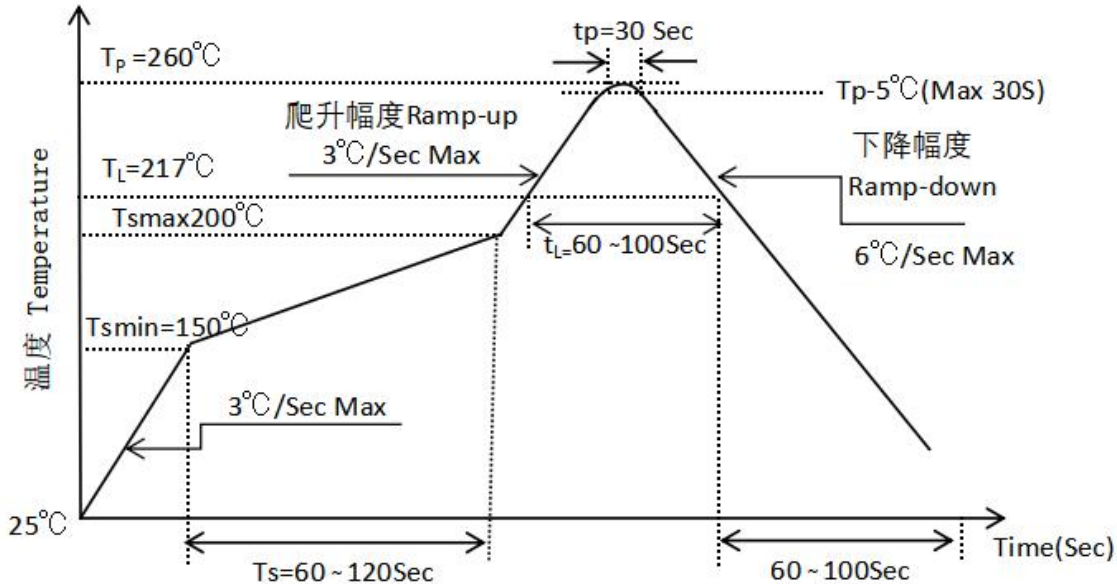
尺寸编号 Dimension No.	A	B	D0	D1	E	F
尺寸(mm) Dimension(mm)	4.4±0.1	7.4±0.1	1.5+0.1/-0	1.5±0.1	1.75±0.1	7.5±0.1
尺寸编号 Dimension No.	P0	P1	P2	t	W	K
尺寸(mm) Dimension(mm)	4.0±0.15	8.0±0.1	2.0±0.1	0.25±0.03	16.0±0.2	2.4±0.1

13. 焊接温度曲线 Temperature Profile Of Soldering

• 回流焊温度曲线 Reflow soldering

建议在下面所示的温度和时间分布条件下, 进行一次回流焊作业, 不得超过三次

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



项目 Item	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
预热温度 Preheat Temperature	T_s	150	200	°C
预热时间 Preheat Time	t_s	60	120	s
升温速率 Ramp-Up Rate (T_L to T_p)	-	-	3	°C/s
液相线温度 Liquidus Temperature	T_L	217		°C
高于液相线温度(T_L)的时间 Time above Liquidus Temperature T_L	t_L	60	100	s
峰值温度 Peak Temperature	T_p	-	260	°C
T_c 在(T_p-5)和 T_p 之间的时间 Time During Which T_c Is Between (T_p-5) and T_p	t_p	-	30	s
降温速率 Ramp-down Rate(T_p to T_L)	-	-	6	°C/s